

## MEMORANDUM OF UNDERSTANDING

This Memorandum of Understanding (MOU) is made on this day, the 1<sup>st</sup> of March, 2015 between:

**Techno India NJR, Institute of Technology, Plot T, Bhamas(RIICO) Industrial Area, Kaladwas, Udaipur, Rajasthan 313003.** (hereinafter referred to as 'TINJR' which expression shall include its representatives, successors and assignees) of one part

AND

**Eduvance, the educational arm of Vanmat Technologies Pvt. Ltd. having its registered office located at 202 Mary Anne Heights, Santacruz (East), Mumbai 400055,** (hereinafter referred to as "Eduvance" which expression shall include its representatives, successors and assignees) of other part.

TINJR and Eduvance are jointly referred to as 'Parties' in this MOU.

WHEREAS: TINJR has expressed interest in appointing Eduvance as an Employability Assessment Partner

In consideration of the mutual obligations herein contained, the parties agree as follows:

### OBJECTIVE AND SCOPE OF WORK

#### EDUVANCE RESPONSIBILITIES

1. Conduct assessment of the students and faculty members of TINJR based on the skills that Eduvance has an expertise in (As enlisted in Annexure 1)
2. Allow TINJR to use Eduvance's automated evaluation platforms for evaluating the skills mentioned in Annexure 1.
3. Recommend highly skilled candidates to companies that Eduvance has a tie up with.

#### TINJR RESPONSIBILITIES

1. Assign one faculty member as a point of contact to act as a liaison with Eduvance for coordination of Eduvance's responsibilities.
2. Appoint Eduvance as Employability Assessment Partner
3. Give students and faculty of TINJR, an exposure to the automated evaluation platforms.

## VALIDITY

4. This MOU is valid for five years from the date of signing of this MOU. Thereafter the MOU may be renewed for such term and on conditions as may be agreed between the Parties.

## NO ASSIGNMENT

5. Neither party without the written consent of the other may assign either the benefit or the burden of this MOU to anybody.

## TERMINATION

6. Either party may terminate the MOU for cogent and logical reasons, by giving to the other party 30 days' notice in writing. There will no financial obligations on either party of any sort due to the termination of this MOU.

## NOTICES

7. Notices would be deemed to have been given provided they are sent in writing by registered mail and a copy of the same is faxed to either of the parties by the other party to the following addresses.

**CEO,**  
**Eduvance (Vanmat Technologies Pvt. Ltd).**  
A 202 Mary Anne Heights,  
3<sup>rd</sup> Golibar Road,  
Santacruz (East), Mumbai 400055  
Ph.No.: +91-9820749235

**Director**  
**Techno India NJR Institute of Technology**  
Plot T, Bhamas(RIICO) Industrial Area,  
Kaladwas,  
Udaipur, Rajasthan 313003  
Ph. No- 0294 265 0214

## ENTIRE AGREEMENT

8. This document represents the entire agreement between the Parties regarding the subject matter of this MOU and can only be amended or modified by an agreement in writing signed by the Parties hereto.


## LEGAL EFFECT

9. This document is **not intended** to impose any legal obligation whatsoever on either party (whether based in contract, tort or under statutory law). The parties **do not intend to be bound by any agreement** until both agree to and sign a definitive written contract. Neither party can rely on any promises inconsistent with this paragraph. This paragraph supersedes all other conflicting language.

**SIGNATURES**

10. This MOU will come into effect on the day date of signature of the representative of both parties as given :

For TINJR :

For Techno India NJR Institute of Technology  
  
(R.S. Vyas)  
Director

For VANMAT

Signature: \_\_\_\_\_

Signature: \_\_\_\_\_

Name: Raj Shekhar Vyas  
Title: Director, Techno India NJR  
Date: 01-03-2015

Name: Dr. Jonathan Joshi  
Title: C.E.O, Eduvance  
Date: 01-03-2015

## ANNEXURE 1

1. Field Programmable Gate Array (FPGA) design
2. VHDL/Verilog programming
3. Front-end VLSI design
4. Back-end VLSI Design
5. VLSI Verification
6. Internet of Things
7. Printed Circuit Board (PCB) design
8. PCB Manufacturing
9. Embedded Systems Design
10. System on Chip Design
11. PLC Programming